SCAS347E - MARCH 1994 - REVISED JUNE 1998

- **EPIC™** (Enhanced-Performance Implanted **CMOS) Submicron Process**
- Typical V_{OLP} (Output Ground Bounce) $< 0.8 \text{ V at V}_{CC} = 3.3 \text{ V}, T_A = 25^{\circ}\text{C}$
- Typical V_{OHV} (Output V_{OH} Undershoot) $> 2 \text{ V at V}_{CC} = 3.3 \text{ V}, T_{A} = 25^{\circ}\text{C}$
- **Supports Mixed-Mode Signal Operation on** All Ports (5-V Input/Output Voltage With 3.3-V V_{CC})
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- **Package Options Include Plastic** Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) **Packages**

DB, DW, OR PW PACKAGE (TOP VIEW)

			1
OE1	[] 1	O 24	Vcc
A1	2	23] Y1
A2	3	22] Y2
A3	4	21] Y3
A4	5	20] Y4
A5	6	19] Y5
A6	7	18] Y6
A7	8	17] Y7
A8	9	16] Y8
A9	10	15] Y9
A10	[] 11	14] Y10
GND	12	13	OE2

description

This 10-bit buffer/bus driver is designed for 1.65-V to 3.6-V V_{CC} operation.

The SN74LVC828A provides a high-performance bus interface for wide data paths or buses carrying parity.

The 3-state control gate is a 2-input AND gate with active-low inputs so that if either output-enable (OE1 or OE2) input is high, all ten outputs are in the high-impedance state. The SN74LVC828A provides inverting data at its outputs.

Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of these devices as translators in a mixed 3.3-V/5-V system environment.

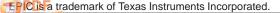
To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN74LVC828A is characterized for operation from -40°C to 85°C.

FUNCTION TABLE

		INPUTS	OUTPUT	
	OE1	OE2	Α	Υ
I	L	L	L	Н
ı	L	L	Н	L
I	Н	X	X	Z
	X	Н	X	Z

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

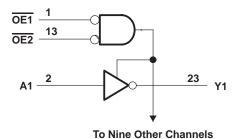




logic symbol[†]

1 OE1 ΕN 13 OE2 23 **Y1 A1** 3 22 **A2 Y2** 4 21 **Y3 A3** 5 20 Α4 **Y4** 6 19 Y5 **A5** 7 18 A6 **Y6** 8 17 **Y7** Α7 9 16 **Y8 A8** 10 15 **A9 Y9** 11 14 A10 Y10

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V _{CC}	
Input voltage range, V _I (see Note 1)	–0.5 V to 6.5 V
Voltage range applied to any output in the high-impedance or power-off state, V _O	
(see Note 1)	0.5 V to 6.5 V
Voltage range applied to any output in the high or low state, VO	
(see Notes 1 and 2)	–0.5 V to V _{CC} + 0.5 V
Input clamp current, I _{IK} (V _I < 0)	–50 mA
Output clamp current, I _{OK} (V _O < 0)	–50 mA
Continuous output current, I _O	±50 mA
Continuous current through V _{CC} or GND	±100 mA
Package thermal impedance, θ _{JA} (see Note 3): DB package	104°C/W
DW package	
PW package	120°C/W
Storage temperature range, T _{stg}	–65°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
 - 2. The value of VCC is provided in the recommended operating conditions table.
 - 3. The package thermal impedance is calculated in accordance with JESD 51.



[†]This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

recommended operating conditions (see Note 4)

			MIN	MAX	UNIT
V/00	Supply voltage	Operating	1.65	3.6	V
VCC	Supply voltage	Data retention only	1.5		V
		V _{CC} = 1.65 V to 1.95 V	0.65 × V _{CC}		V
V _{IH} F	High-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7		
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	2		
		V _{CC} = 1.65 V to 1.95 V		0.35 × V _{CC}	
V_{IL}	Low-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		0.7	V
	V _{CC} = 2.7 V to 3.6 V			0.8	
٧ _I	Input voltage		0	5.5	V
\/-	Output voltage	0	Vcc	V	
VO		3 state	0	5.5	V
		V _{CC} = 1.65 V		-4	
1	High level cutout current	$V_{CC} = 2.3 \text{ V}$		-8	mA
ЮН	High-level output current	V _{CC} = 2.7 V		-12	
		V _{CC} = 3 V		-24	
	V _{CC} = 1.65 V			4	
1	Low lovel output ourrent	V _{CC} = 2.3 V		8	
IOL	Low-level output current $V_{CC} = 2.7 \text{ V}$			12	mA
		V _{CC} = 3 V		24	
Δt/Δν	Input transition rise or fall rate		0	10	ns/V
TA	Operating free-air temperature		-40	85	°C

NOTE 4: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

SN74LVC828A **10-BIT BUFFER/DRIVER** WITH 3-STATE OUTPUTS

SCAS347E - MARCH 1994 - REVISED JUNE 1998

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CO	ONDITIONS	vcc	MIN	TYP [†]	MAX	UNIT
	I _{OH} = -100 μA			V _{CC} -0.2			
	I _{OH} = -4 mA	1.65 V	1.2				
Voн	IOH = -8 mA	2.3 V	1.7			V	
VOH	404		2.7 V	2.2			V
	$I_{OH} = -12 \text{ mA}$		3 V	2.4			
	I _{OH} = -24 mA		3 V	2.2			
	I _{OL} = 100 μA		1.65 V to 3.6 V			0.2	
V _{OL}	I _{OL} = 4 mA	1.65 V			0.45		
	I _{OL} = 8 mA	2.3 V			0.7	٧	
	I _{OL} = 12 mA	2.7 V			0.4		
	I _{OL} = 24 mA		3 V			0.55	
lį	V _I = 0 to 5.5 V		3.6 V			±5	μΑ
l _{off}	V _I or V _O = 5.5 V		0			±10	μΑ
loz	V _O = 0 to 5.5 V		3.6 V			±10	μΑ
	$V_I = V_{CC}$ or GND		2.21/			10	^
Icc	$3.6 \text{ V} \le \text{V}_{\text{I}} \le 5.5 \text{ V}^{\ddagger}$	IO = 0	3.6 V			10	μΑ
ΔlCC	One input at V _{CC} – 0.6 V,	Other inputs at V _{CC} or GND	2.7 V to 3.6 V			500	μΑ
Ci	V _I = V _{CC} or GND		3.3 V		5		pF
Со	$V_O = V_{CC}$ or GND		3.3 V		7		pF

[†] All typical values are at $V_{CC} = 3.3 \text{ V}$, $T_A = 25^{\circ}\text{C}$. ‡ This applies in the disabled state only.

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 through 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)		V _{CC} = 1.8 V V _{CC} = 2.5 V ± 0.15 V ± 0.2 V		V _{CC} = 2.7 V		V _{CC} = 3.3 V ± 0.3 V		UNIT	
	(INFOT)	(0011-01)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
^t pd	А	Υ	§	§	§	§		7.1	1	6.7	ns
t _{en}	ŌĒ	Υ	§	§	§	§		8.5	1	7.3	ns
^t dis	ŌĒ	Y	§	§	§	§		7.3	1.8	6.7	ns
t _{sk(o)} ¶										1	ns

[§] This information was not available at the time of publication.

operating characteristics, $T_A = 25^{\circ}C$

PARAMETER			TEST CONDITIONS	V _{CC} = 1.8 V ± 0.15 V	V _{CC} = 2.5 V ± 0.2 V	V _{CC} = 3.3 V ± 0.3 V	UNIT	
			CONDITIONS	TYP	TYP	TYP		
Power dissipation capacitance		Outputs enabled	f = 10 MHz	§	§	24	nE	
C _{pd}	per buffer/driver	Outputs disabled	1 = 10 MH2	§	§	7	pF	

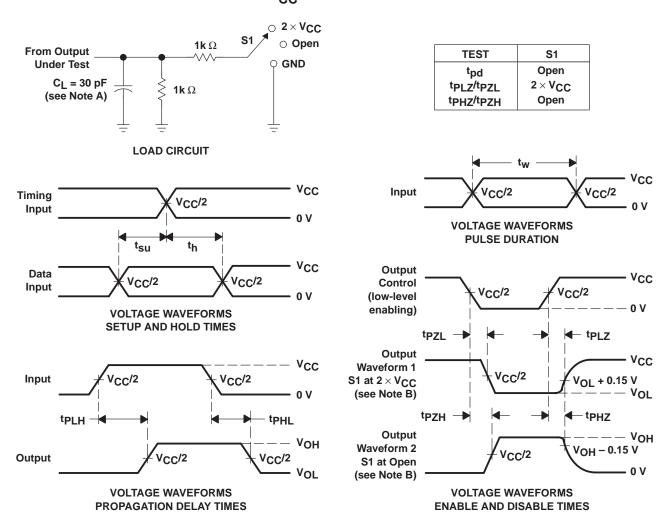
[§] This information was not available at the time of publication.



 $[\]P$ Skew between any two outputs of the same package switching in the same direction

SCAS347E - MARCH 1994 - REVISED JUNE 1998

PARAMETER MEASUREMENT INFORMATION $V_{CC} = 1.8 \text{ V} \pm 0.15 \text{ V}$

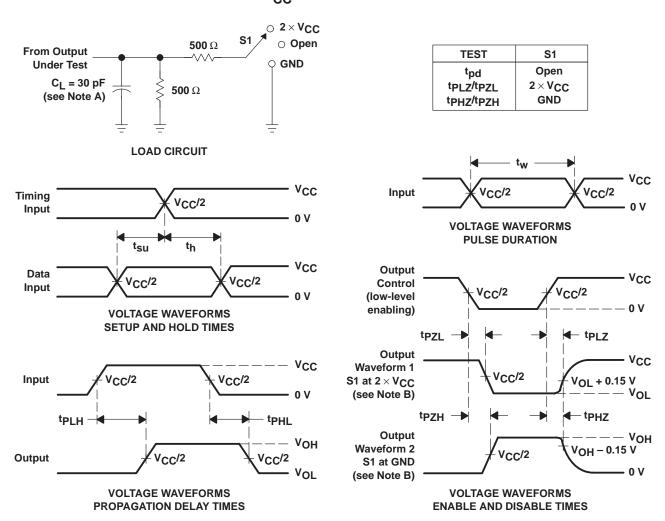


NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , $t_f \leq$ 2 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. t_{PZL} and t_{PZH} are the same as t_{en}.
- G. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION $V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$



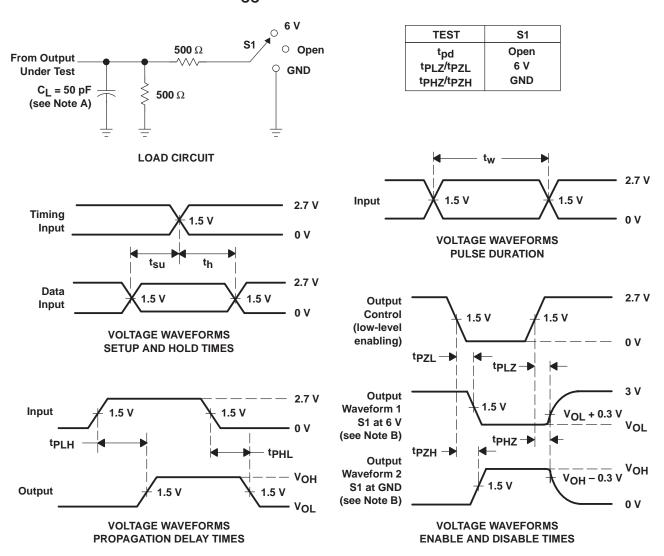
NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50 \ \Omega$, $t_f \leq 2 \ ns$, $t_f \leq 2 \ ns$.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLZ and tpHZ are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.

Figure 2. Load Circuit and Voltage Waveforms



PARAMETER MEASUREMENT INFORMATION V_{CC} = 2.7 V AND 3.3 V \pm 0.3 V



- NOTES: A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_O = 50 Ω , t_f \leq 2.5 ns, t_f \leq 2.5 ns.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. tpzL and tpzH are the same as ten.
 - G. tpLH and tpHL are the same as tpd.

Figure 3. Load Circuit and Voltage Waveforms



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